



## 2900MHz, 350W, 32V High Power RF LDMOS FETs

### ITCH29350C2



### Description

The ITCH29350C2 is a 350-watt, internally matched LDMOS FETs, designed for multiple applications with frequencies at 2900MHz for ISM and RF Energy applications

- Typical Performance in 2.8/2.9G application boards with devices soldered

$V_{DS}=32V, I_{DQ}=500mA$ , Pulsed CW 10% 25us

Freq	P1dB	P1dB	P1dB Eff	P1dB Gain	P3dB	P3dB	P3dB Eff
(MHz)	(dBm)	(W)	%	dB	(dBm)	(W)	%
2900	55.28	337.62	43	10	56.0	400	45

Freq	P1dB	P1dB	P1dB Eff	P1dB Gain	P3dB	P3dB	P3dB Eff
(MHz)	(dBm)	(W)	%	dB	(dBm)	(W)	%
2800	55.06	320.55	42	9.9	55.94	392.37	45

### Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Internally Matched for Ease of Use
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Excellent thermal stability, low HCI drift
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DSS}$	70	Vdc
Gate--Source Voltage	$V_{GS}$	-10 to +10	Vdc
Operating Voltage	$V_{DD}$	+32	Vdc
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Case Operating Temperature	$T_c$	+150	°C
Operating Junction Temperature	$T_j$	+225	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case Case Temperature 80°C, 350W Pulsed Output	$R_{\theta JC}$	0.1	°C/W

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22--A114)	Class 2

**Table 4. Electrical Characteristics** (TA = 25 °C unless otherwise noted)



Characteristic	Symbol	Min	Typ	Max	Unit
<b>DC Characteristics</b>					
Drain-Source Breakdown Voltage ( $V_{GS}=0V$ ; $I_D=100\mu A$ )	$V_{DSS}$	65	70	—	V
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28 V$ , $V_{GS} = 0 V$ )	$I_{DSS}$	—	—	10	$\mu A$
Gate--Source Leakage Current ( $V_{GS} = 6 V$ , $V_{DS} = 0 V$ )	$I_{GSS}$	—	—	1	$\mu A$
Gate Threshold Voltage ( $V_{DS} = 28V$ , $I_D = 600 \mu A$ )	$V_{GS(th)}$	—	1.9	—	V
Gate Quiescent Voltage ( $V_{DS} = 28 V$ , $I_{DQ} = 500 mA$ , Measured in Functional Test)	$V_{GS(Q)}$	—	3	3.5	V

**Functional Tests (In Innegration Test Fixture, 50 ohm system) :**  $V_{DS} = 32 Vdc$ ,  $I_{DQ} = 500 mA$ ,  $f = 2900 MHz$ , Pulse CW Signal Measurements.  
(Pulse Width=20  $\mu s$ , Duty cycle=10%)

Power Gain @ $P_{3dB}$	$G_p$	8	9	—	dB
Drain Efficiency@ $P_{3dB}$	$\eta_D$	43	45	—	%
3dB Compression Point	$P_{3dB}$	350	400	—	W
Input Return Loss	IRL	—	-7	—	dB

**Load Mismatch of per Section (On Test Fixture, 50 ohm system):**  $V_{DD} = 32 Vdc$ ,  $I_{DQ} = 500 mA$ ,  $f = 2900 MHz$

VSWR 5:1 at 350W pulse CW Output Power	No Device Degradation
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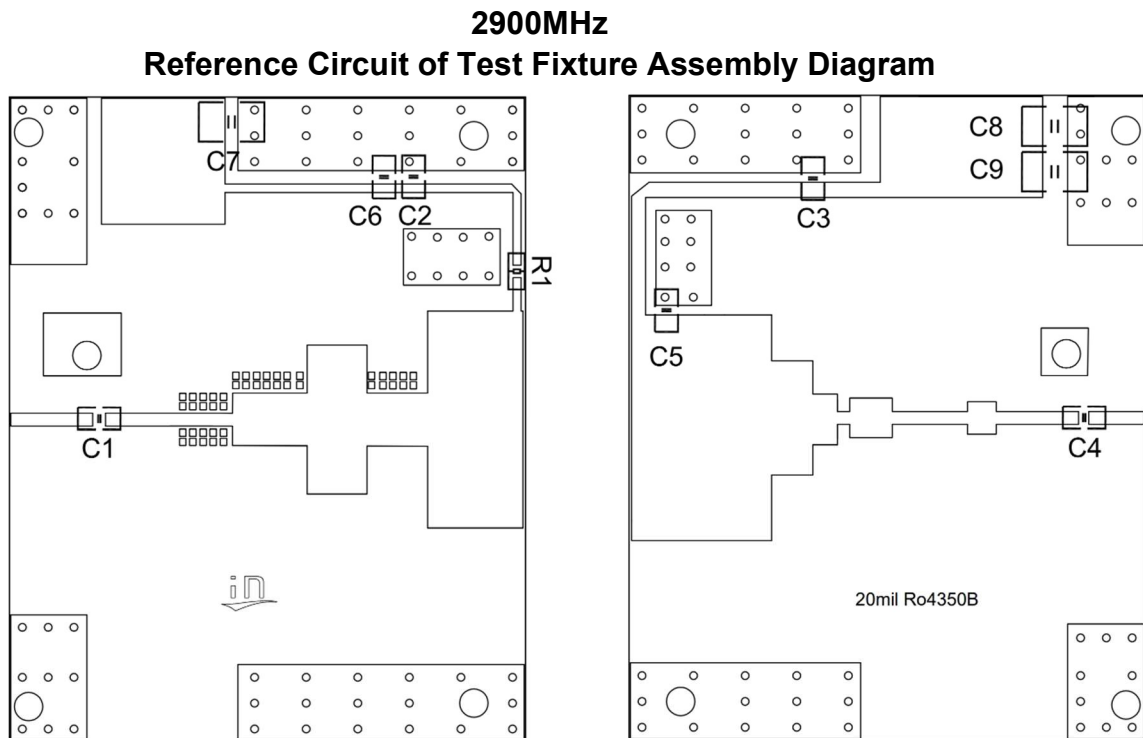


Figure 1. Test Circuit Component Layout (2900MHz)

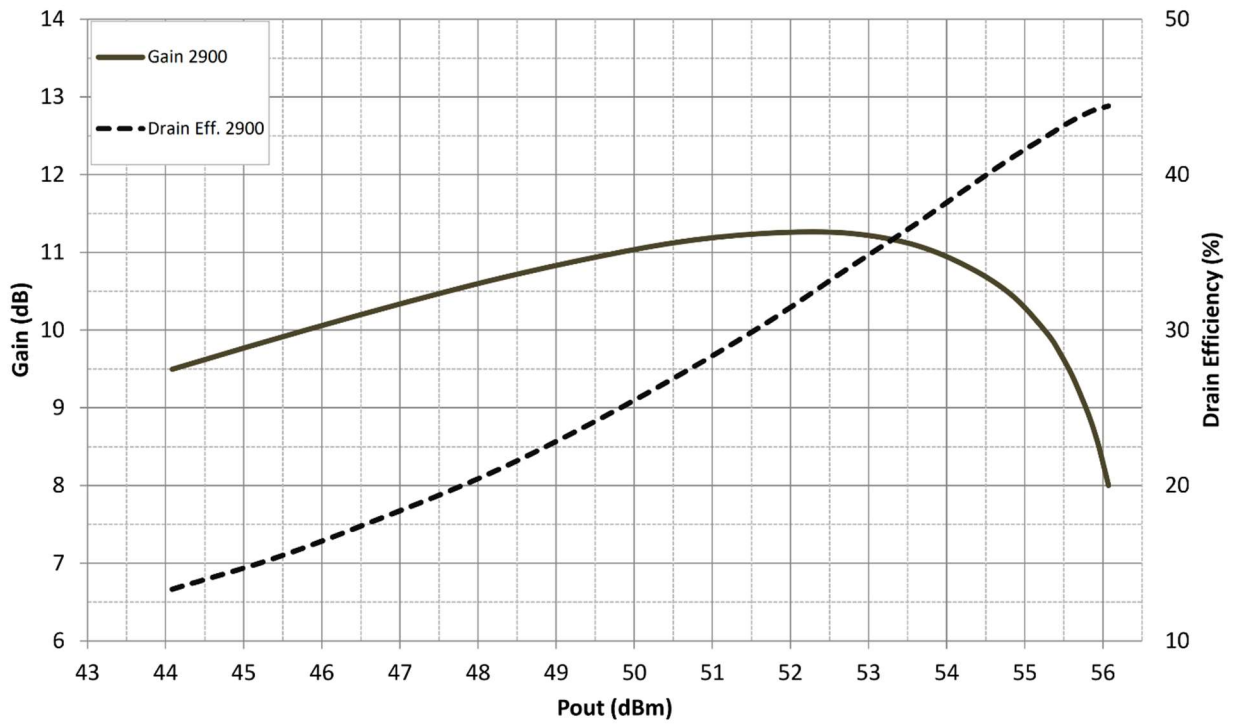


Table 1. Test Circuit Component Designations and Values

Reference	Footprint	Value	Quantity
C1, C2, C3, C4,	0805	15pF/250V	4
C5	0805	0.5pF/250V	1
C6	0805	1uF/50V	1
C7, C8, C9	1210	10uF/100V	3
R1	0603	10R	1
U1	C6	ITCH29350C2	1

### TYPICAL CHARACTERISTICS

Figure 2. Power Gain and Drain Efficiency as Function of Pulsed CW Output Power



**2800MHz**

**Reference Circuit of Test Fixture Assembly Diagram**

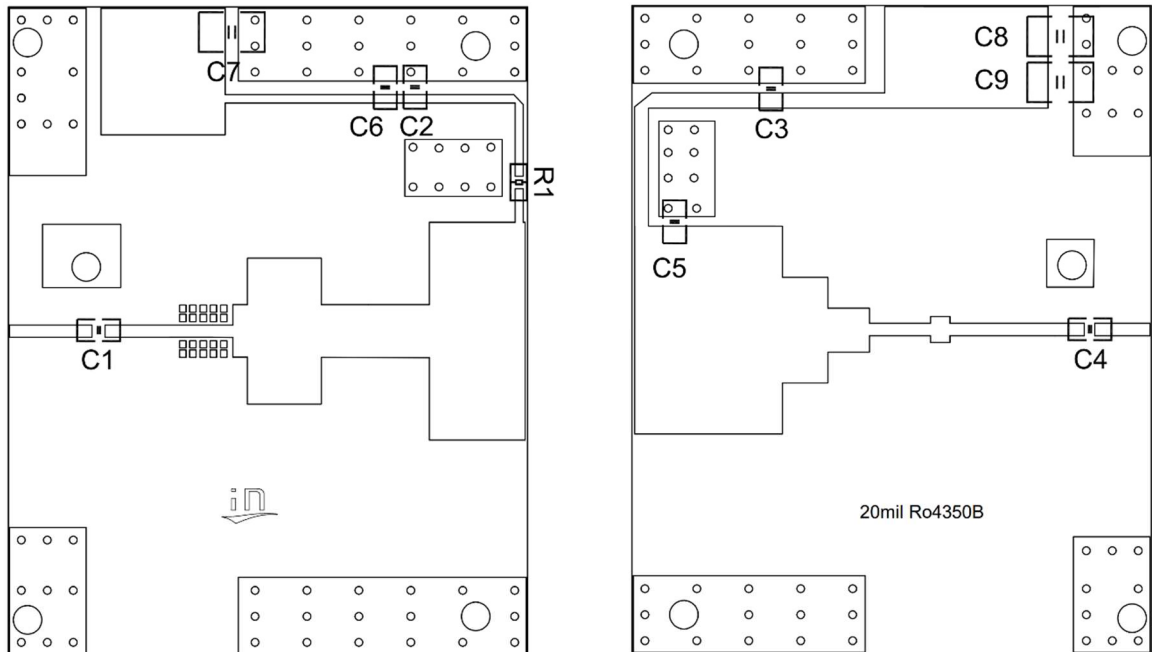


Figure 3. Test Circuit Component Layout (2800MHz)

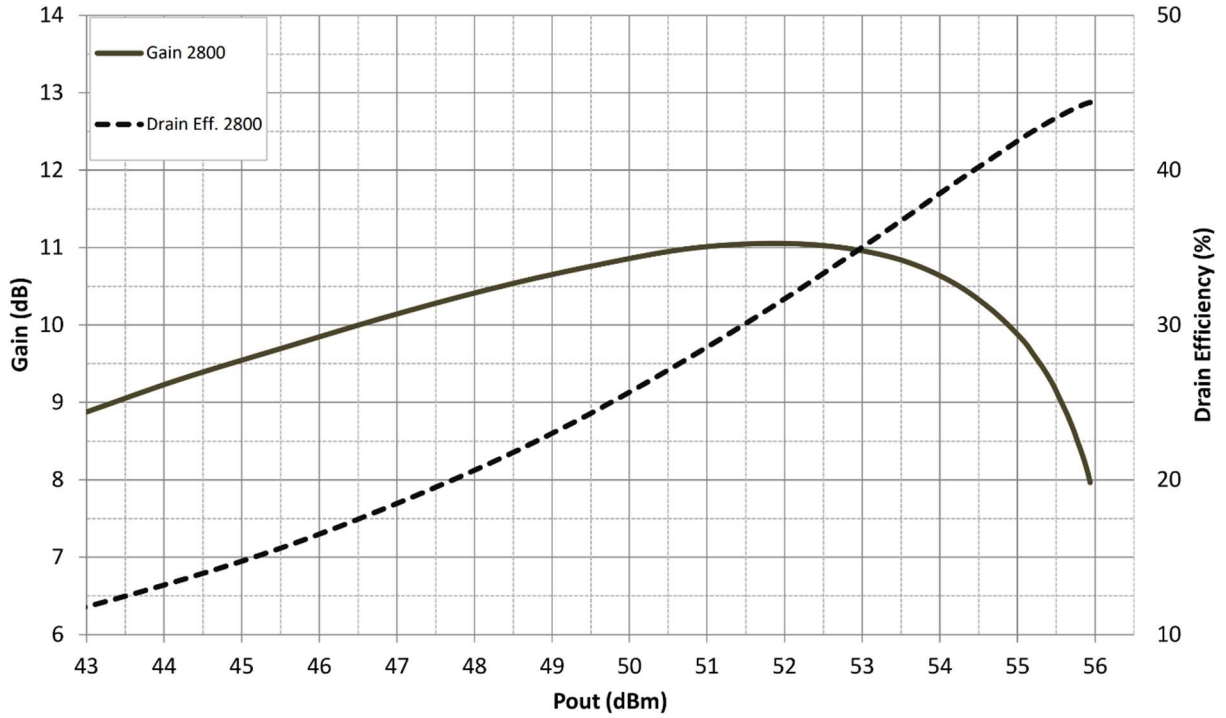
Table 6. Test Circuit Component Designations and Values

Reference	Footprint	Value	Quantity
C1, C2, C3, C4,	0805	15pF/250V	4
C5	0805	0.5pF/250V	1
C6	0805	1uF/50V	1
C7, C8, C9	1210	10uF/100V	3
R1	0603	10R	1
U1	C2	ITCH29350C2	1



### TYPICAL CHARACTERISTICS

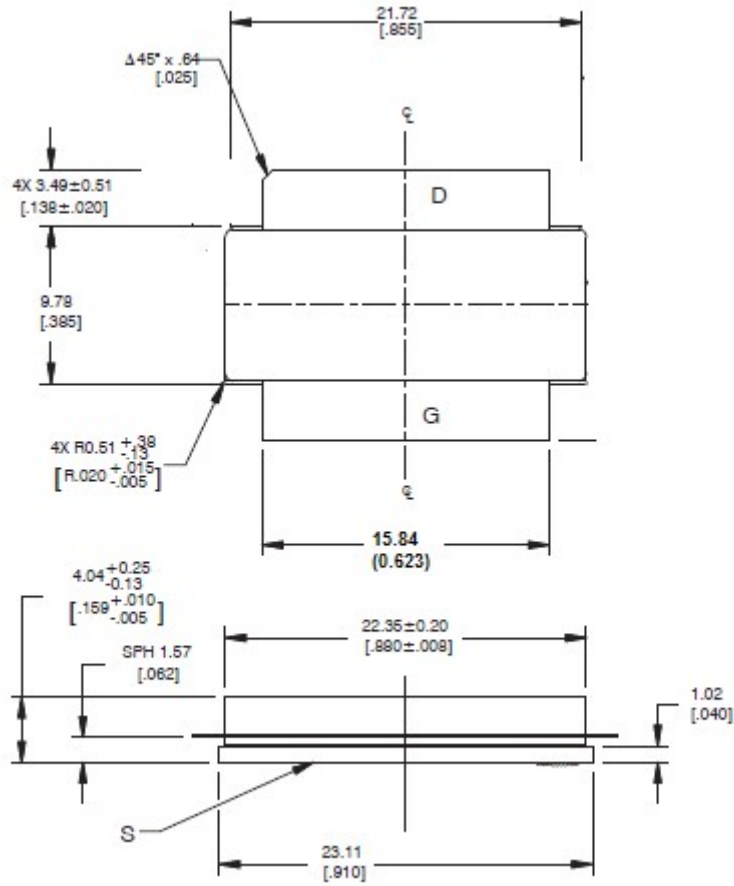
Figure 3. Power Gain and Drain Efficiency as Function of Pulsed CW Output Power





### Package Outline

Flangeless ceramic package;



OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-C2					09/27/2018



## Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2024/3/22	V1.0	Preliminary Datasheet Creation

Application data based on ZBB-24-08/10

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